

## SPECIFICATION FOR SMT TCXO

### MtronPTI P/N M6164S039

#### Electrical Specifications:

Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
Frequency of Operation	F <sub>O</sub>		10.000000		MHz	
Frequency Tolerance		-1.0		+1.0	ppm	@ +25°C
<b>Frequency Stabilities</b>						
Frequency vs. Temperature	ΔF/F			1.0	ppm	(F <sub>MAX</sub> -F <sub>MIN</sub> )/2
Aging		-5.0		+5.0	ppm	10 years
Frequency vs. Supply	F <sub>VS</sub>		± 0.02	± 0.1	ppm	For 5% voltage change
Frequency vs. Load	F <sub>L</sub>		± 0.02	± 0.1	ppm	For 5% load change
<b>Output</b>						
Output Type			Clipped Sine Wave			
Output Load			10kΩ // 10pF			
Output Level	V <sub>OUT</sub>	0.8			V <sub>pk-pk</sub>	
Tristate Function		Logic "1", or floating, output Enabled. Logic "0", output Disabled.				Pad 8
Startup Time	T <sub>SU</sub>			10	ms	
<b>Additional Specifications</b>						
SSB Phase Noise (Under Static Conditions)			-101		dBc/Hz	@ 10Hz Offset
			-123			@ 100Hz Offset
			-145			@ 1kHz Offset
			-155			@ 10kHz Offset
			-155			@ 100kHz Offset
G-sensitivity			1.3		ppb/g	
<b>Supply Voltage &amp; Power Consumption</b>						
Operating Voltage	V <sub>DD</sub>	3.135	3.3	3.465	V <sub>DC</sub>	
Operating Current	I <sub>DD</sub>			4.0	mA	

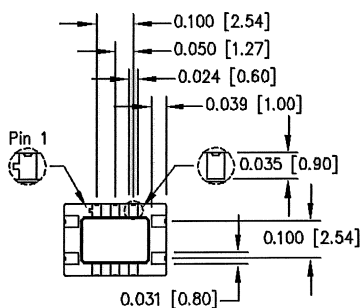
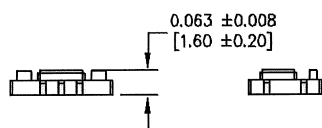
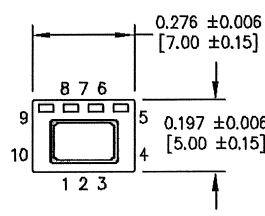
#### Environmental & Mechanical Requirements:

Operating Temperature	T <sub>A</sub>	-40		+85	°C	
Storage Temperature	T <sub>S</sub>	-55		+125	°C	
Mechanical Shock	Per MIL-STD-202, Method 213, Condition C (100 g's, 6 ms duration, ½ sine wave)					
Vibration	Per MIL-STD-202, Method 201 & 204 (10 g's from 10-2000 Hz)					
Solderability	Per MIL-STD-202, Method 208, except steam aging is not required					
Max. Soldering Conditions	See solder profile, Figure 1					
Package Type	5.0 x 7.0 x 2.0mm, 10-pad Ceramic Leadless Chip Carrier. RoHS Compliant.					

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### Mechanical, Marking and Layout Information:

Pad	Function
1	N/C
2	N/C
3	N/C
4	Ground/Case
5	Output
6	N/C
7	N/C
8	Tristate
9	+V <sub>DD</sub>
10	N/C



#### SUGGESTED SOLDER PAD LAYOUT

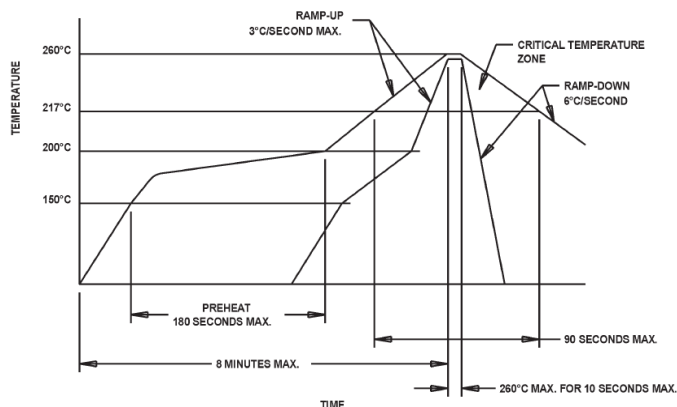
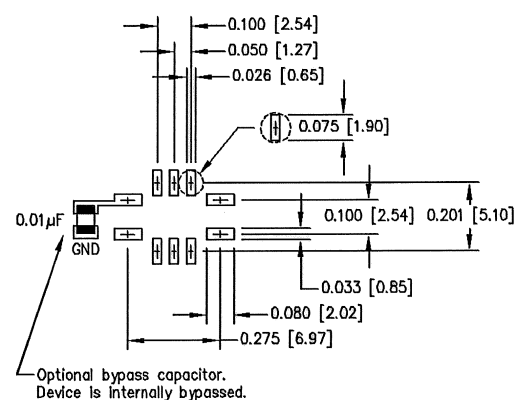


Figure 1

### Data Sheet Revision Table:

Date	Rev.	Author	Details of Revision
05/09/17	0	MM	Original Release.